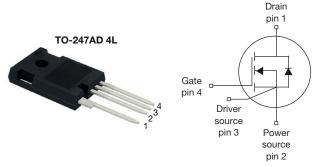


## MaxSiC® 1200 V N-Channel SiC MOSFET



Marking Code: 120A045SL

PRODUCT SUMMARY			
V <sub>DS</sub> (V) at T <sub>J</sub> max.	1200		
R <sub>DS(on)</sub> typ. (mΩ) at 25 °C	V <sub>GS</sub> = 18 V 45		
Q <sub>g</sub> typ. (nC)	83		
I <sub>D</sub> (A)	51		
C <sub>oss</sub> typ. (pF)	96		
P <sub>D</sub> (W)	254		
Configuration	Single		

#### **FEATURES**

- · Fast switching speed
- Short circuit withstand time 3 µs





### **APPLICATIONS**

- Solar Inverters
- Energy Storage Systems
- UPS (uninterruptible power supplies)

ORDERING INFORMATION	
Package	TO-247AD 4L
Lead (Pb)-free and halogen-free	MXP120A045SL-GE3

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C,	unless otherwise	noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		$V_{DS}$	1200	
Gate-source voltage		$V_{GS}$	-10 / +22	V
Recommended operation voltage of gate-source		$V_{GSOP}$	-5 to -3 / +18	
Continuous drain current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	51	^
Pulsed drain current <sup>a</sup>	·	I <sub>DM</sub>	102	A
Short-circuit withstand time <sup>b</sup>		T <sub>SC</sub>	3	μs
Maximum power dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	254	W
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Soldering recommendations (peak temperature)	For 10 s		260	°C
Single pulse avalanche energy <sup>c</sup>		E <sub>AS</sub>	200	mJ

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{GS}$  = 18 V,  $V_{DS}$  = 800 V,  $R_{g(ext)}$  = 20  $\Omega$ , verified by the design / characterization
- c.  $T_J = 25$  °C,  $V_{DD} = 120$  V, L = 1 mH,  $V_{GS} = 18$  V,  $I_{AS} = 20$  A



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	40	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.59	C/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	-					ı	
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D =$	1 mA	1200			V
Cata source threshold voltage (N)	V	$V_{DS} = V_{GS}, I_D =$	5 mA	-	2.8	-	V
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 5$ mA,	T <sub>J</sub> = 175 °C	-	1.9	-	V
Gate-source leakage	lasa	$V_{GS} = 22 \text{ V}, V_{DS}$	s = 0 V	-	-	100	nA
Gate-source leakage	I <sub>GSS</sub>	$V_{GS} = -10 \text{ V}, V_{D}$	<sub>S</sub> = 0 V	-	-	-100	IIA
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 1200 \text{ V}, V_{C}$	<sub>SS</sub> = 0 V	-	-	10	μΑ
		$V_{GS} = 15 \text{ V}, I_D = 15 \text{ V}$	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 26 A		60	75	
Drain-source on-state resistance	R <sub>DS(on)</sub>	$V_{GS} = 18 \text{ V}, I_D = 10 \text{ V}$	= 26 A	-	45	56	mΩ
		$V_{GS} = 18 \text{ V}, I_D = 26 \text{ A}$	, T <sub>J</sub> = 175 °C	-	82	-	
Transconductance	gfs	$V_{DS} = 10 \text{ V}, I_D = 10 \text{ V}$	= 26 A	-	11	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>			-	2523	-	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$	/, f = 100 KHz	-	96	-	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	3	-	
Total gate charge	$Q_g$				83	-	
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = -5 \text{ V} \sim 18 \text{ V}, I_D = 26$	$8 A, V_{DS} = 800 V$	-	24	-	nC
Gate-drain charge	$Q_{gd}$	1   [		-	23	-	
Gate Resistance	$R_g$	$V_{DS} = 0 \text{ V, f} = 1$	MHz	-	3	-	Ω
Switching Characteristics							
Town on delections	1		T <sub>J</sub> = 25 °C	-	20	-	
Turn-on delay time	t <sub>d(on)</sub>		T <sub>J</sub> = 175 °C	-	18	-	
Diag time			T <sub>J</sub> = 25 °C	-	17	-	- ns
Rise time	t <sub>r</sub>		T <sub>J</sub> = 175 °C	-	16	-	
Time off delegations			T <sub>J</sub> = 25 °C	-	26	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GS} = -5 \text{ V} \sim 18 \text{ V},$	T <sub>J</sub> = 175 °C	-	29	-	
Fall time	+	$I_D = 26 \text{ A}, V_{DS} = 800 \text{ V},$ $R_{q(ext)} = 4.4 \Omega$	T <sub>J</sub> = 25 °C	-	10	-	
raii tiirie	t <sub>f</sub>	g(oxt)	T <sub>J</sub> = 175 °C	-	10	=.	
Turn on quitables anarry	_		T <sub>J</sub> = 25 °C	-	285	-	- μJ
Turn-on switching energy	E <sub>on</sub>		T <sub>J</sub> = 175 °C	-	252	-	
T off and table an analysis	-	_	T <sub>J</sub> = 25 °C	-	86	-	
Turn-off switching energy	E <sub>off</sub>		T <sub>J</sub> = 175 °C	-	85	-	
<b>Body Diode Ratings and Characteristic</b>	C						
Forward diode voltage	V <sub>SD</sub>	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 13 A, T <sub>J</sub> = 25 °C		-	4.9	-	V
Continuous diode forward current	I <sub>SD</sub>	V <sub>GS</sub> = -5 V, T <sub>J</sub> = 25 °C		-	-	37	_
Pulsed diode forward current	I <sub>SDM</sub>			-	-	102	Α
Reverse recovery time	t <sub>rr</sub>	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 26 A, V <sub>R</sub> = 800 V, di/dt = 1000 A/μs		-	19	-	ns
Reverse recovery charge	Q <sub>rr</sub>			-	83	-	nC
Reverse recovery current	I <sub>RRM</sub>			-	7	-	Α

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

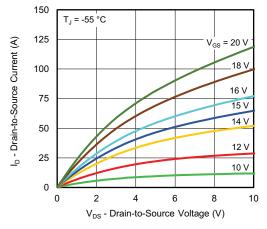
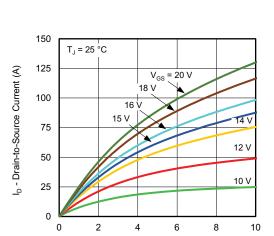


Fig. 1 - Typical Output Characteristics



 $V_{DS}$  - Drain-to-Source Voltage (V) Fig. 2 - Typical Output Characteristics

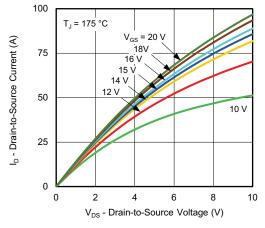


Fig. 3 - Typical Output Characteristics

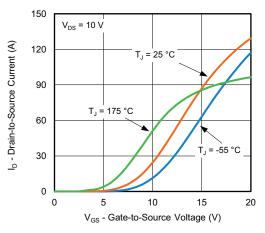


Fig. 4 - Typical Transfer Characteristics

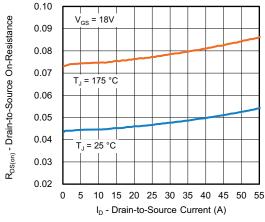


Fig. 5 - Normalized On-Resistance vs. Drain Current

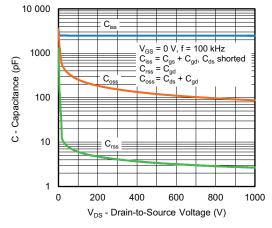


Fig. 6 - Typical Capacitance vs. Drain-to-Source Voltage



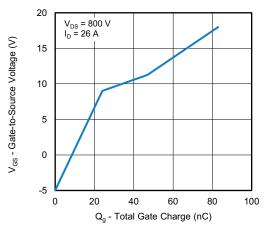


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

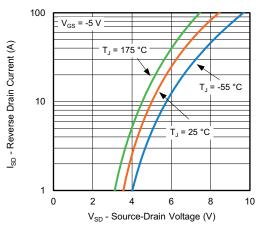


Fig. 10 - Typical Source-Drain Diode Forward Voltage

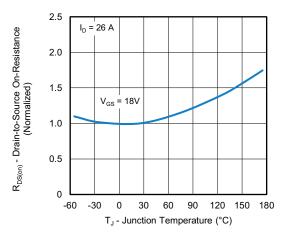


Fig. 8 - Normalized On-Resistance vs. Temperature

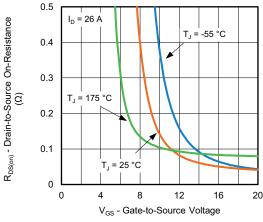


Fig. 11 - On-Resistance vs. Gate-to-Source Voltage

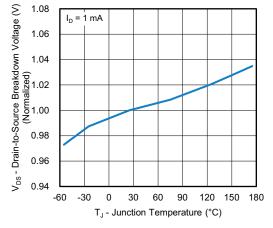


Fig. 9 - Drain-to-Source Voltage vs. Temperature

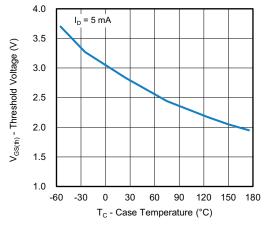


Fig. 12 - Threshold Voltage vs. Case Temperature

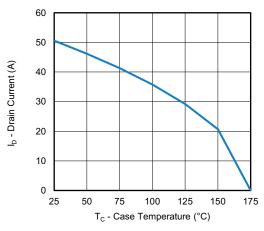


Fig. 13 - Drain Current vs. Case Temperature

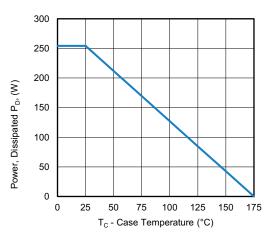


Fig. 15 - Power, Dissipated P<sub>D</sub> vs. Case Temperature

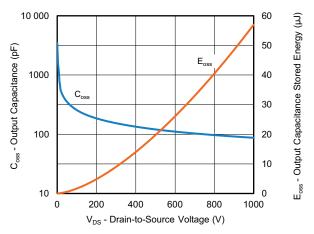


Fig. 14 - Output Capacitance and its Stored Energy vs.
Drain-to-Source Voltage

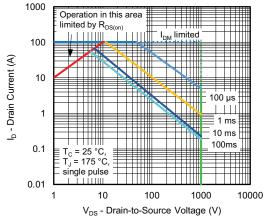


Fig. 16 - Safe Operating Area

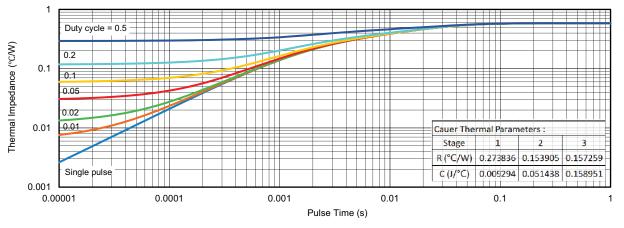


Fig. 17 - Transient Thermal Impedance



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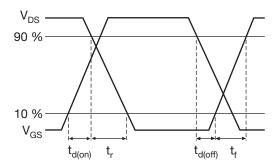


Fig. 18 - Waveforms of Switching Time

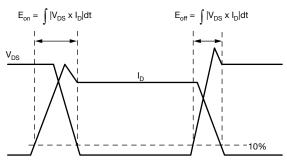


Fig. 19 - Waveforms for Switching Energy

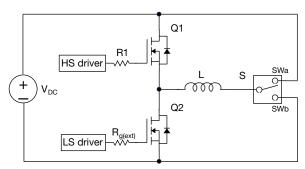


Fig. 20 - Switching and Reverse Diode Characteristics Measurement Circuit

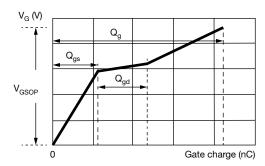


Fig. 21 - Waveforms for Gate Charge

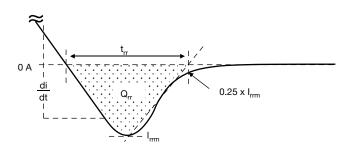


Fig. 22 - Waveforms for Reverse Recovery

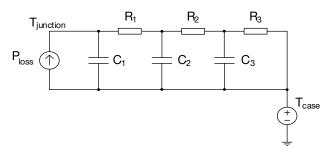


Fig. 23 - Thermal Equivalent Circuit

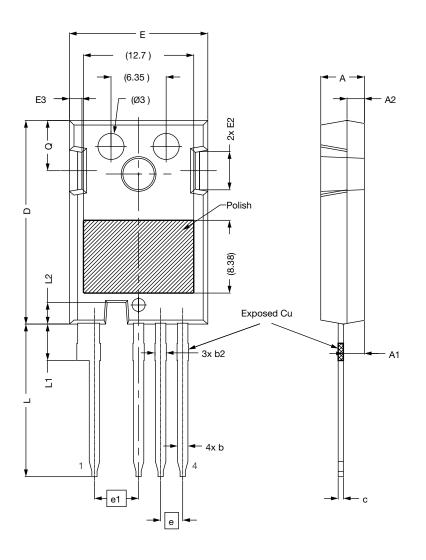
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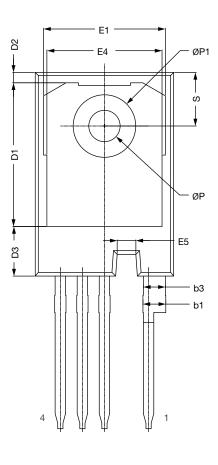
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# Case Outline for TO-247AD 4L Package

### **FACILITY CODE: 9**







# **Package Information**

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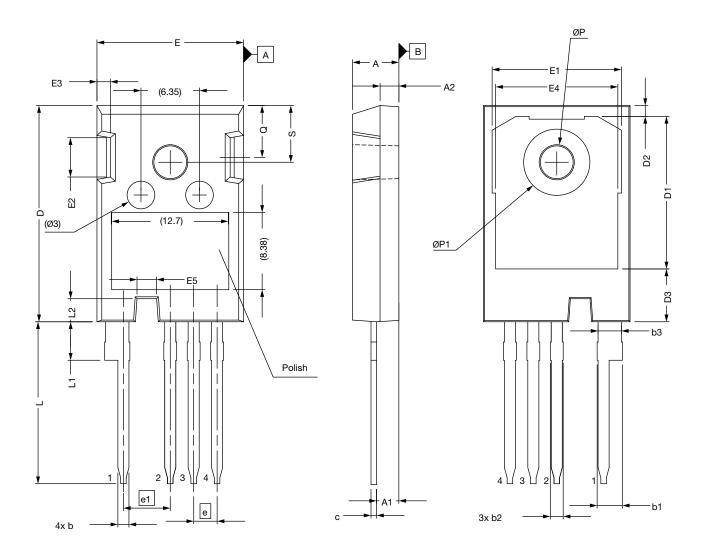
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DIM.	MILLIMETERS		
DIWI.	MIN.	MAX.	
A	4.83	5.21	
A1	2.29	2.54	
A2	1.91	2.16	
b	1.07	1.33	
b1	2.39	2.94	
b3	1.07	1.60	
С	0.55	0.68	
D	23.30	23.60	
D1	16.25	17.65	
D2	0.95	1.25	
E	15.75	16.13	
E1	13.10	14.15	
E2	3.68	5.10	
E3	1.00	1.90	
E4	12.38	13.43	
E5	1.95	2.35	
e	2.54 BSC.		
e1	5.08 BSC.		
L	17.31	17.82	
L1	3.97	4.37	
L2	2.35	2.65	
ØP	3.51	3.65	
Q	5.49	6.00	
S	6.04	6.30	

#### Notes

- All dimensions are in mm. Angles are in degrees
- Dimension D and E do not include mold flash
- All metal surfaces: tin plated, except area of cut
- Dimensioning and toleranceing confirm to ASME Y14.5M-1994
- Creepage 1 is 8.58 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2). Creepage 2 is 7.95 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4

### **FACILITY CODE: N**





# **Package Information**

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## Vishay MaxPower Semiconductor

DIM.	MILLIMETERS			
DIM.	MIN.	NOM.	MAX.	
Α	4.83	5.02	5.21	
A1	2.29	2.41	2.54	
A2	1.91	2.00	2.16	
b	1.07	1.20	1.33	
b1	2.39	2.67	2.94	
b2	1.07	1.30	1.60	
b3	2.39	2.53	2.69	
С	0.55	0.60	0.68	
D	23.30	23.45	23.60	
D1	16.25	16.55	17.65	
D2	0.95	1.19	1.25	
D3	5.55	5.71	6.01	
Е	15.75	15.94	16.13	
E1	13.10	14.02	14.15	
E2	3.68	4.40	5.10	
E3	1.00	1.45	1.90	
E4	12.38	13.26	13.43	
E5	1.95	2.15	2.35	
е		2.54 BSC.		
e1		5.08 BSC.		
L	17.31	17.57	17.82	
L1	3.97	4.19	4.37	
L2	2.35	2.50	2.65	
ØP	3.51	3.61	3.65	
ØP1	7.19 ref.			
Q	5.49	5.79	6.00	
S	6.04	6.17	6.30	
FCN: \$25-0851-Rev. C. 18-Jul-202	- 5	1		

ECN: S25-0851-Rev. C, 18-Jul-2025

DWG: 6121

### Notes

- All dimensions are in mm
- Dimension D and E do not include mold flash.
- Creepage 1 is 8.40 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2). Creepage 2 is 7.70 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4



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